

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 61-291967

(43)Date of publication of application : 22.12.1986

(51)Int.Cl.

C23C 14/34

G11B 7/26

G11B 11/10

(21)Application number : 60-132275

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(22)Date of filing : 18.06.1985

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(54) TARGET FOR SPUTTERING

(57)Abstract:

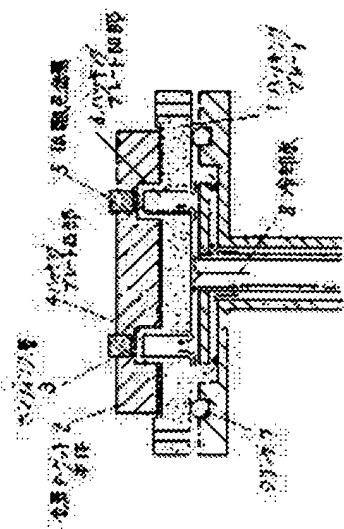
PURPOSE: To obtain a high-quality thin film which is free from defects by the melting or bumping of a low melting metal by providing projections to part of the bonding surface of a composite target contg. said metal and bonding said metal directly to a backing plate.

CONSTITUTION: The target body 2 consisting of a metal such as Te, Ni or non-metal such as Al_2O_3 , SiC is adhered by a bonding layer 3 consisting of In alloy material onto the backing plate 1 made of copper, etc.

The projections 4 are provided to the bonding surface of the plate 1 and the low melting metal 5 such as Sn, Bi embedded into the body 2 is bonded directly to the plate

1. The projections 4 preferably form part of a hollow cylinder coaxial with the center of the body 2. Recesses

6 are preferably formed on the rear surface of the projections 4 so that cooling water 8 for the target circulates therein. The cooling efficiency is improved and the thin film having high quality is obtd. in a short period by such constitution.



LEGAL STATUS



[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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